RoHS

HALOGEN



6.5 m Ω , Bi-Directional Battery Switch in Compact WCSP

DESCRIPTION

The SiP32101 bidirectional switch features reverse blocking capability to isolate the battery from the system. The internal switch has an ultra-low 6.5 m Ω (typ at 3.3 V) on-resistance and operates from a +2.3 V to +5.5 V input voltage range, making the device ideal battery-disconnect switch for high-capacity battery applications.

The SiP32101 has slew rate control, making it ideal in large load capacitor as well as high-current load switching applications. The device is also highly efficient, consuming a mere 10 pA (typ.) current in shutdown and 15 pA while operating.

The SiP32101 has an active low enable and can interface directly with a low voltage control signal.

The SiP32101 is available in an ultra compact 12-Bump, 1.3 mm x 1.7 mm, 0.4 mm pitch WCSP package with top side lamination. The device operates over the temperature of -40 $^{\circ}$ C to +85 $^{\circ}$ C.

FEATURES

- · Bi-directional ON and OFF
- Ultra low R_{on} , 6.5 m Ω (typ.) at 3.3 V
- Wide input voltage, 2.3 V to 5.5 V
- · Slew rate controlled turn on
- Ultra-low quiescent current: 15 pA
- EN pin with integrated pull down resistor
- Compact 12-Bump, 1.3 mm x 1.7 mm x 0.55 mm WCSP package
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Smartphones and tablets
- Digital still / video cameras
- Portable meters and test instruments
- · Communication devices with embedded batteries
- · Portable medical and healthcare systems
- Data storage

TYPICAL APPLICATION CIRCUIT

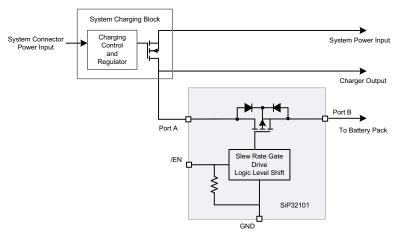


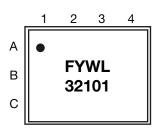
Fig. 1 - Typical Application Circuit

ORDERING INFORMATION					
PART NUMBER	MARKING	PACKAGE	TEMPERATURE		
SiP32101DB-T1-GE1	32101	12-Bump, 1.3 mm x 1.7 mm, 0.4 mm pitch WCSP package	-40 °C to 85 °C		

Note

• GE1 denotes halogen-free and RoHS-compliant

MARKING





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ABSOLUTE MAXIMUM RATINGS					
PARAMETER	CONDITIONS	LIMIT	UNIT		
V V	Reference to GND	-0.3 to 6			
V_{PA}, V_{PB}	Pulse at 1 ms reference to GND ^a	-1.6	V		
V _{EN}	Reference to GND	-0.3 to 6			
Maximum Continuous Switch Current		5	Α		
Operating Temperature		-40 to 85			
Operating Junction Temperature		125	°C		
Storage Temperature		-65 to 150			
Thermal Resistance (θ _{JA}) ^b		104	°C/W		
Power Dissipation (P _D) ^{b,c}	T _A = 70 °C	529	mW		

Note

- a. Negative current injection up to 300 mA.
- b. All bumps soldered to 1 inch x 1 inch, 2 oz. copper, 4 layers PC board.
- c. Derate 9.6 mW/°C above $T_A = 70$ °C.

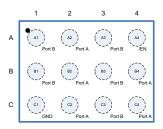
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating/conditions for extended periods may affect device reliability.

SPECIFICATIONS							
		TEST CONDITIONS UNLESS SPECIFIED	LIMITS				
PARAMETER	SYMBOL	$\begin{split} V_{\text{IN}} = V_{\text{PA}}/V_{\text{PB}} = 2.3 \text{ V to } 5.5 \text{ V, } T_{\text{A}} = -40 \text{ °C to } 85 \text{ °C} \\ \text{(Typical values are at V}_{\text{PA}}, V_{\text{PB}} = 4.2 \text{ V,} \\ C_{\text{PA}}, C_{\text{PB}} = 0.1 \mu\text{F, } T_{\text{A}} = 25 \text{ °C)} \end{split}$	MIN.a	TYP.b	MAX.a	UNIT	
Power Supply							
Operating Voltage ^c	$V_{PA/PB}$		2.3	-	5.5	V	
Quiescent Current	IQ	$V_{\overline{EN}} = 0.4 \text{ V}$, no load	-	0.015	300		
Shutdown Current	I _{SHDN}	$V_{\overline{EN}} = V_{IN}$, no load	-	0.010	300	nA	
Internal FET	Internal FET						
On-Resistance	R _{DS(on)}	$V_{PA}/V_{PB} = 2.3 \text{ V}, I_L = 500 \text{ mA}, T_A = 25 ^{\circ}\text{C}$	-	8	13	mΩ	
On-Resistance		$V_{PA}/V_{PB} = 3.3 \text{ V}, I_L = 500 \text{ mA}, T_A = 25 \text{ °C}$	-	6.5	10		
Control							
EN Input Logic-Low Voltage ^c	V_{IL}		-	-	0.4	V	
EN Input Logic-High Voltage ^c	V_{IH}		1.4	-	-	1 °	
EN Pull Down Resistor	R _{EN}	$V_{PA}/V_{PB} = 5.5 \text{ V}, V_{\overline{EN}} = 2.3 \text{ V}$	-	500	700	kΩ	
Timing							
Output Turn-On Delay Time	t _{d(on)}		-	0.5	-		
Output Turn-On Rise Time	t _r	V 40V B 100 0 0 01 05 T 05 00	-	1	-		
Output Turn-Off Delay Time	t _{d(off)}	$V_{IN} = 4.2 \text{ V}, R_L = 100 \Omega, C_L = 0.1 \mu\text{F}, T_A = 25 ^{\circ}\text{C}$	-	2.4	-	- ms -	
Output Turn-Off Fall Time	t _f		-	1	-		

Notes

- a. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum.
- b. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
- c. For V_{IN} outside this range consult typical $\overline{\text{EN}}$ threshold curve.

BUMP CONFIGURATION

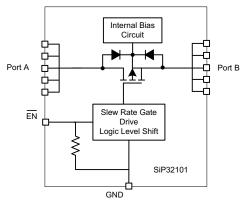


Top view (solder bumps on bottom)

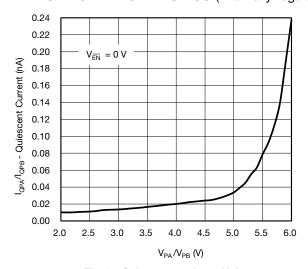
Fig. 2 - WCSP12, 1.3 mm x 1.7 mm

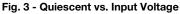
BUMP DESCRIPTION			
BUMP NUMBER	NAME	FUNCTION	
A1, B1, A3, B3, C3	PB	Power Port B	
C1	GND	Ground	
A2, B2, C2, B4, C4	PA	Power Port A	
A4	EN	Control logic - active low enable input	

FUNCTIONAL BLOCK DIAGRAM



TYPICAL CHARACTERISTICS (internally regulated 25 °C, unless otherwise noted)





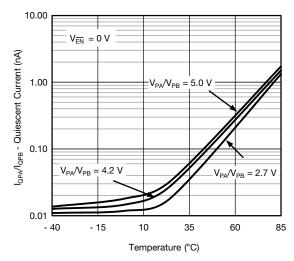


Fig. 4 - Quiescent vs Temperature



TYPICAL CHARACTERISTICS (internally regulated 25 °C, unless otherwise noted)

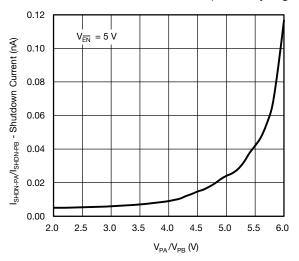


Fig. 5 - Shutdown Current vs. Input Voltage

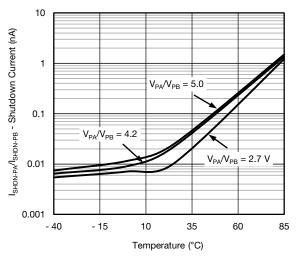


Fig. 6 - Shutdown Current vs.Temperature

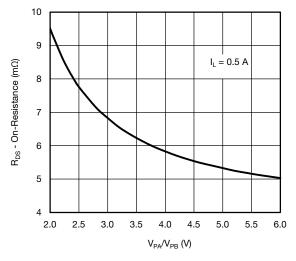


Fig. 7 - On Resistance vs. Input Voltage

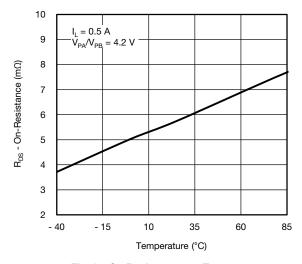


Fig. 8 - On Resistance vs. Temperature

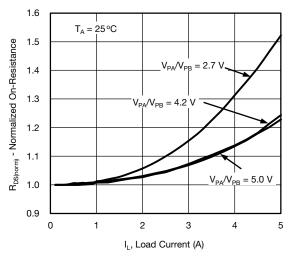


Fig. 9 - Normalized On Resistance vs. Load Current

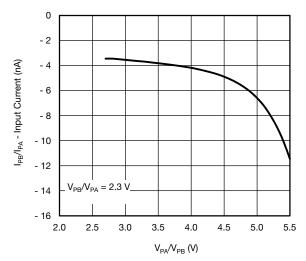


Fig. 10 - Reverse Blocking Current (I_{RB}) vs. Output Voltage



TYPICAL CHARACTERISTICS (internally regulated 25 °C, unless otherwise noted)

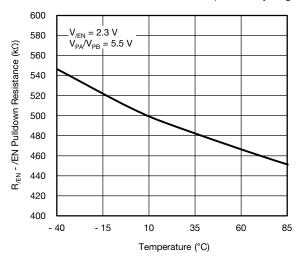


Fig. 11 - EN Pulldown Resistance vs. Temperature

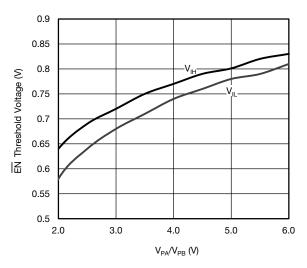


Fig. 12 - EN Threshold Voltage vs. Input Voltage

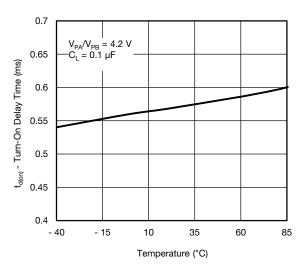


Fig. 13 - Turn-on Delay Time vs. Temperature

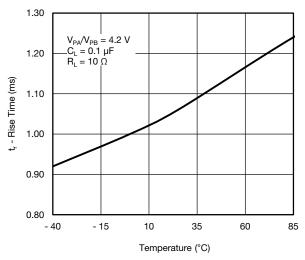


Fig. 14 - Rise Time vs Temperature

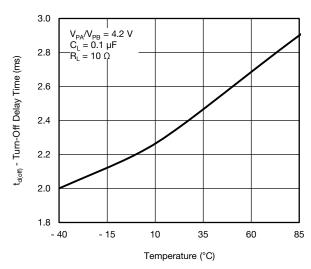


Fig. 15 - Turn-off Delay Time vs. Temperature

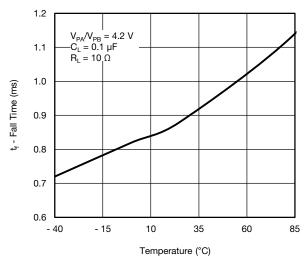


Fig. 16 - Fall Time vs. Temperature

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DETAILED DESCRIPTION

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The SiP32101 is available in an ultra compact 12-Bump, 1.3 mm x 1.7 mm, 0.4 mm pitch WCSP package with top side lamination. The device operates over the temperature of -40 $^{\circ}$ C to +85 $^{\circ}$ C.

REVERSE CURRENT BLOCKING

SiP32101 bidirectional switch prevents current flowing from either port to the other when the device is disabled.

EN INPUT

SiP32101 has an active-low enable pin which can interface with low voltage GPIO directly. The switch is on when $\overline{\text{EN}}$ is low and off when $\overline{\text{EN}}$ is high. The EN pin has an integrated pull down resistor.

SWITCH ON AND OFF PERFORMANCE

The SiP32101 has slew rate control. This minimizes the inrush current and provides a soft turn on.

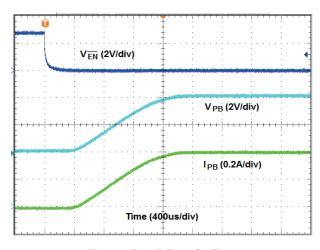


Fig. 17 - Port B Turn-On Time (VPA = 4.2 V, RL = 10 Ω , CL = 0.1 μ F)

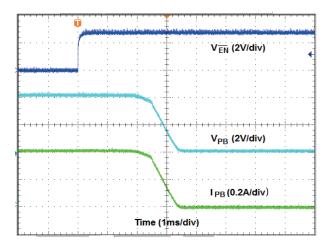


Fig. 18 - Port B Turn-Off Time ($V_{PA} = 4.2 \text{ V}, R_L = 10 \Omega, C_L = 0.1 \mu\text{F}$)

DEVICE PIN OUT

Device pin out is designed for ease of layout.

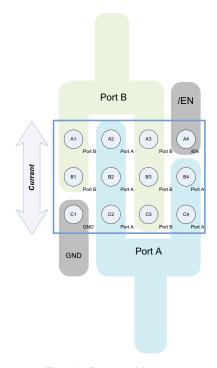


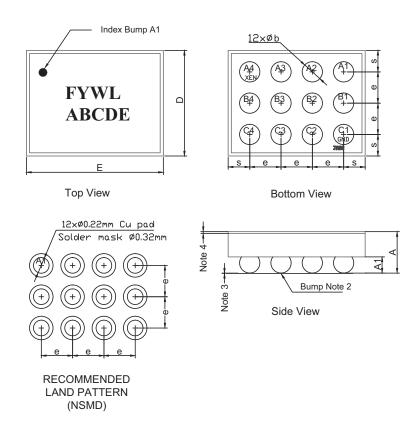
Fig. 19 - Proposed Layout

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WCSP12: 12 Bumps

(3 x 4, 0.4 mm pitch, 208 µm bump height, 1.71 mm x 1.31 mm die size)



	MILLIMETERS (5)			INCHES		
DIMENSION	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	0.515	0.530	0.545	0.0203	0.0209	0.0215
A1	0.183	0.208	0.233	0.0072	0.0082	0.0092
b	0.234	0.260	0.312	0.0092	0.0102	0.0123
е	0.400			0.0157		
S	0.235	0.255	0.275	0.0093	0.0100	0.0108
D	1.270	1.310	1.350	0.0500	0.0516	0.0531
E	1.670	1.710	1.750	0.0657	0.0673	0.0689

Notes (unless otherwise specified)

- (1) Laser mark on the silicon die back coated with an epoxy film.
- (2) Bumps are SAC396.
- (3) 0.050 max. co-planarity.
- (4) Laminate tape thickness is 0.022 mm.
- (5) Use millimeters as the primary measurement.

ECN: S13-2510-Rev. B, 16-Dec-13

DWG: 6017



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Revision: 02-Oct-12 Document Number: 91000

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